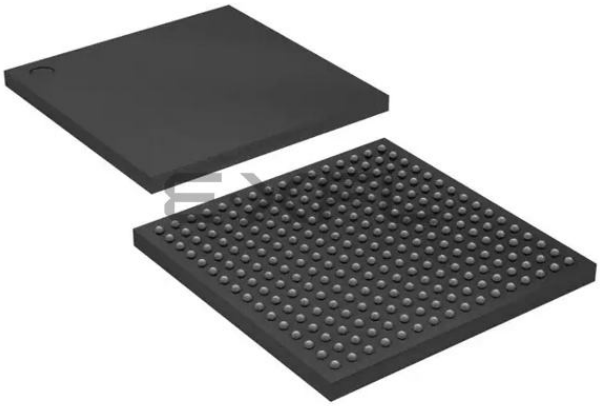

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Active
Number of LABs/CLBs	288
Number of Logic Elements/Cells	4608
Total RAM Bits	119808
Number of I/O	158
Number of Gates	-
Voltage - Supply	1.15V ~ 1.25V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	256-LBGA
Supplier Device Package	256-FBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep2c5f256c7n

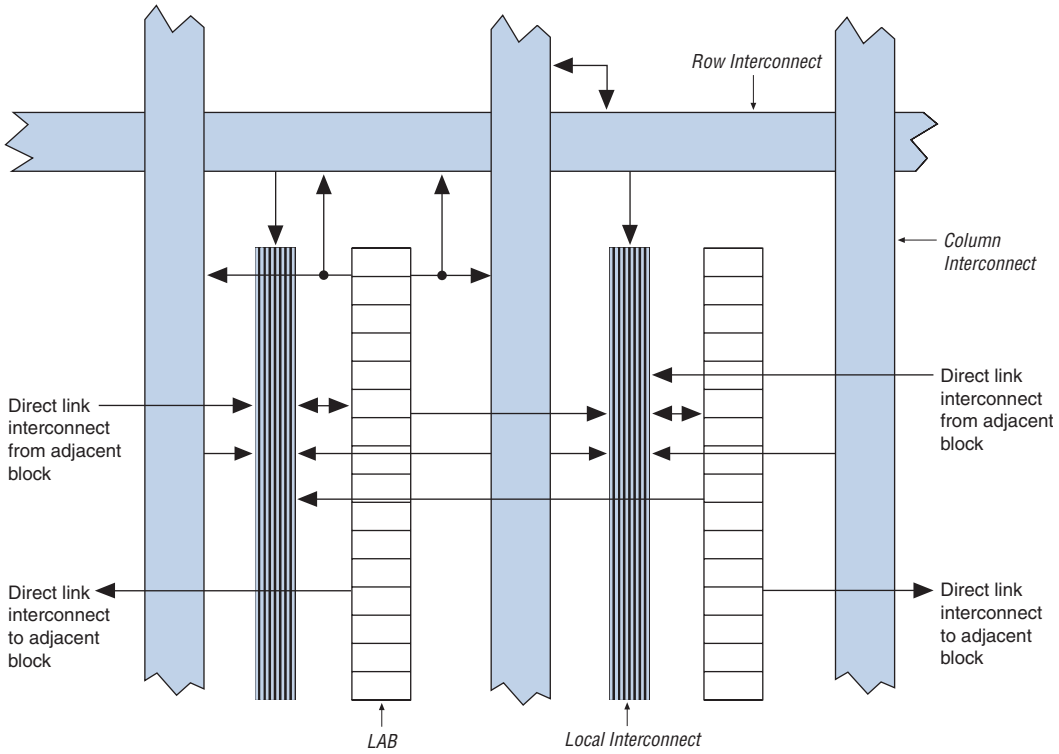
Logic Array Blocks

Each LAB consists of the following:

- 16 LEs
- LAB control signals
- LE carry chains
- Register chains
- Local interconnect

The local interconnect transfers signals between LEs in the same LAB. Register chain connections transfer the output of one LE's register to the adjacent LE's register within an LAB. The Quartus II Compiler places associated logic within an LAB or adjacent LABs, allowing the use of local, and register chain connections for performance and area efficiency. Figure 2–5 shows the Cyclone II LAB.

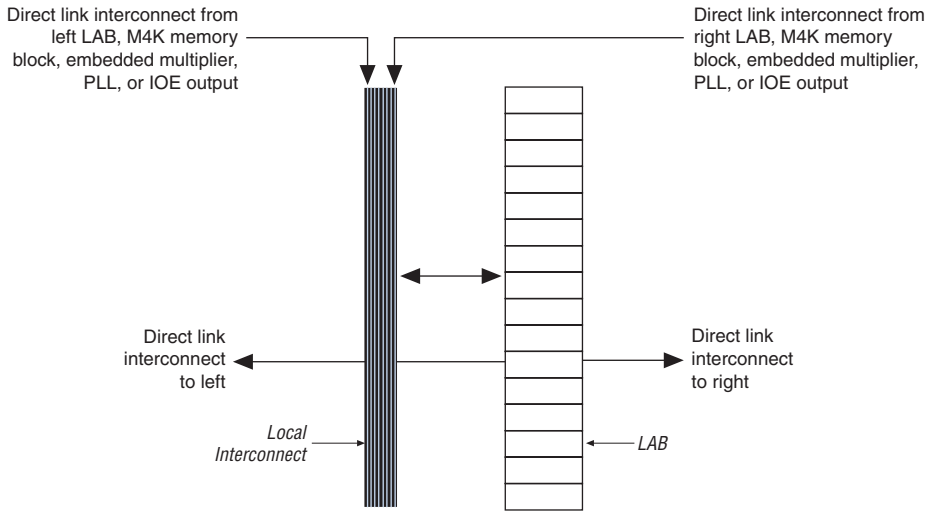
Figure 2–5. Cyclone II LAB Structure



LAB Interconnects

The LAB local interconnect can drive LEs within the same LAB. The LAB local interconnect is driven by column and row interconnects and LE outputs within the same LAB. Neighboring LABs, PLLs, M4K RAM blocks, and embedded multipliers from the left and right can also drive an LAB's local interconnect through the direct link connection. The direct link connection feature minimizes the use of row and column interconnects, providing higher performance and flexibility. Each LE can drive 48 LEs through fast local and direct link interconnects. Figure 2–6 shows the direct link connection.

Figure 2–6. Direct Link Connection

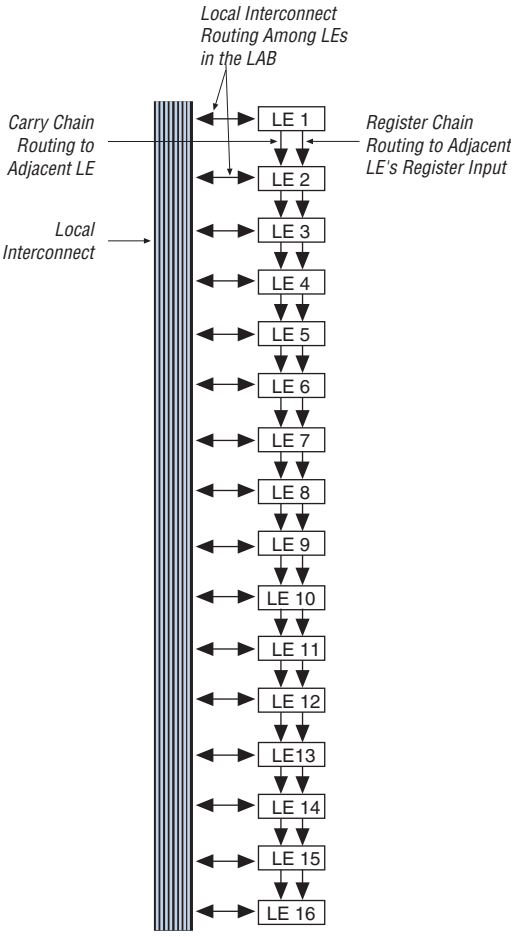


LAB Control Signals

Each LAB contains dedicated logic for driving control signals to its LEs. The control signals include:

- Two clocks
- Two clock enables
- Two asynchronous clears
- One synchronous clear
- One synchronous load

Figure 2–9. Register Chain Interconnects



The C4 interconnects span four LABs, M4K blocks, or embedded multipliers up or down from a source LAB. Every LAB has its own set of C4 interconnects to drive either up or down. Figure 2–10 shows the C4 interconnect connections from an LAB in a column. The C4 interconnects can drive and be driven by all types of architecture blocks, including PLLs, M4K memory blocks, embedded multiplier blocks, and column and row IOEs. For LAB interconnection, a primary LAB or its LAB neighbor (see Figure 2–10) can drive a given C4 interconnect. C4 interconnects can drive each other to extend their range as well as drive row interconnects for column-to-column connections.

Devices Can Be Driven before Power-Up

You can drive signals into the I/O pins, dedicated input pins, and dedicated clock pins of Cyclone II devices before or during power-up or power-down without damaging the device. Cyclone II devices support any power-up or power-down sequence (V_{CCIO} and V_{CCINT}) to simplify system level design.

I/O Pins Remain Tri-Stated during Power-Up

A device that does not support hot socketing may interrupt system operation or cause contention by driving out before or during power-up. In a hot-socketing situation, the Cyclone II device's output buffers are turned off during system power-up or power-down. The Cyclone II device also does not drive out until the device is configured and has attained proper operating conditions. The I/O pins are tri-stated until the device enters user mode with a weak pull-up resistor (R) to 3.3V. Refer to Figure 4–1 for more information.

You can power up or power down the V_{CCIO} and V_{CCINT} pins in any sequence. The V_{CCIO} and V_{CCINT} must have monotonic rise to their steady state levels. (Refer to Figure 4–3 for more information.) The power supply ramp rates can range from 100 µs to 100 ms for non "A" devices. Both V_{CC} supplies must power down within 100 ms of each other to prevent I/O pins from driving out. During hot socketing, the I/O pin capacitance is less than 15 pF and the clock pin capacitance is less than 20 pF. Cyclone II devices meet the following hot-socketing specification.

- The hot-socketing DC specification is $| I_{IOPIN} | < 300$ µA.
- The hot-socketing AC specification is $| I_{IOPIN} | < 8$ mA for 10 ns or less.

This specification takes into account the pin capacitance but not board trace and external loading capacitance. You must consider additional capacitance for trace, connector, and loading separately.

I_{IOPIN} is the current at any user I/O pin on the device. The DC specification applies when all V_{CC} supplies to the device are stable in the powered-up or powered-down conditions. For the AC specification, the peak current duration due to power-up transients is 10 ns or less.

A possible concern for semiconductor devices in general regarding hot socketing is the potential for latch-up. Latch-up can occur when electrical subsystems are hot socketed into an active system. During hot socketing, the signal pins may be connected and driven by the active system before

Table 5–19. M4K Block Internal Timing Microparameters (Part 3 of 3)

Parameter	–6 Speed Grade (1)		–7 Speed Grade (2)		–8 Speed Grade (3)		Unit
	Min	Max	Min	Max	Min	Max	
TM4KCLR	191	—	244	—	244	—	ps
	—	—	217	—	244	—	ps

Notes to Table 5–19:

(1) For the –6 speed grades, the minimum timing is for the commercial temperature grade. The –7 speed grade devices offer the automotive temperature grade. The –8 speed grade devices offer the industrial temperature grade.

(2) For each parameter of the –7 speed grade columns, the value in the first row represents the minimum timing parameter for automotive devices. The second row represents the minimum timing parameter for commercial devices.

(3) For each parameter of the –8 speed grade columns, the value in the first row represents the minimum timing parameter for industrial devices. The second row represents the minimum timing parameter for commercial devices.

Cyclone II Clock Timing Parameters

Refer to Tables 5–20 through 5–34 for Cyclone II clock timing parameters.

Table 5–20. Cyclone II Clock Timing Parameters

Symbol	Parameter
t_{CIN}	Delay from clock pad to I/O input register
t_{COUT}	Delay from clock pad to I/O output register
t_{PLLCIN}	Delay from PLL `inclk` pad to I/O input register
$t_{PLLCOUT}$	Delay from PLL `inclk` pad to I/O output register

EP2C5/A Clock Timing Parameters

Tables 5–21 and 5–22 show the clock timing parameters for EP2C5/A devices.

Table 5–21. EP2C5/A Column Pins Global Clock Timing Parameters (Part 1 of 2)

Parameter	Fast Corner		–6 Speed Grade	–7 Speed Grade (1)	–7 Speed Grade (2)	–8 Speed Grade	Unit
	Industrial/ Automotive	Commercial					
t_{CIN}	1.283	1.343	2.329	2.484	2.688	2.688	ns
t_{COUT}	1.297	1.358	2.363	2.516	2.717	2.717	ns
t_{PLLCIN}	–0.188	–0.201	0.076	0.038	0.042	0.052	ns

Table 5–23. EP2C8/A Column Pins Global Clock Timing Parameters (Part 2 of 2)

Parameter	Fast Corner		–6 Speed Grade	–7 Speed Grade (1)	–7 Speed Grade (2)	–8 Speed Grade	Unit
	Industrial/ Automotive	Commercial					
$t_{PLLCOUT}$	–0.179	–0.189	0.089	0.047	0.045	0.055	ns

Notes to Table 5–23:
(1) These numbers are for commercial devices.
(2) These numbers are for automotive devices.

Table 5–24. EP2C8/A Row Pins Global Clock Timing Parameters

Parameter	Fast Corner		–6 Speed Grade	–7 Speed Grade (1)	–7 Speed Grade (2)	–8 Speed Grade	Unit
	Industrial/ Automotive	Commercial					
t_{CIN}	1.256	1.314	2.270	2.416	2.596	2.606	ns
t_{COUT}	1.258	1.316	2.286	2.429	2.604	2.614	ns
t_{PLLCIN}	–0.276	–0.294	–0.08	–0.134	–0.152	–0.142	ns
$t_{PLLCOUT}$	–0.274	–0.292	–0.064	–0.121	–0.144	–0.134	ns

Notes to Table 5–24:
(1) These numbers are for commercial devices.
(2) These numbers are for automotive devices.

EP2C15A Clock Timing Parameters

Tables 5–25 and 5–26 show the clock timing parameters for EP2C15A devices.

Table 5–25. EP2C15A Column Pins Global Clock Timing Parameters

Parameter	Fast Corner		–6 Speed Grade	–7 Speed Grade (1)	–7 Speed Grade (2)	–8 Speed Grade	Unit
	Industrial/ Automotive	Commercial					
t_{CIN}	1.621	1.698	2.590	2.766	3.009	2.989	ns
t_{COUT}	1.635	1.713	2.624	2.798	3.038	3.018	ns
t_{PLLCIN}	–0.351	–0.372	0.045	0.008	0.046	0.016	ns

I/O Delays

Refer to Tables 5–39 through 5–43 for I/O delays.

Table 5–39. I/O Delay Parameters

Symbol	Parameter
t_{DIP}	Delay from I/O datain to output pad
t_{OP}	Delay from I/O output register to output pad
t_{PCOUT}	Delay from input pad to I/O dataout to core
t_{PI}	Delay from input pad to I/O input register

Table 5–40. Cyclone II I/O Input Delay for Column Pins (Part 1 of 3)

I/O Standard	Parameter	Fast Corner		–6 Speed Grade	–7 Speed Grade (1)	–7 Speed Grade (2)	–8 Speed Grade	Unit
		Industrial/ Automotive	Commer -cial					
LVTTL	t_{PI}	581	609	1222	1228	1282	1282	ps
	t_{PCOUT}	367	385	760	783	854	854	ps
2.5V	t_{PI}	624	654	1192	1238	1283	1283	ps
	t_{PCOUT}	410	430	730	793	855	855	ps
1.8V	t_{PI}	725	760	1372	1428	1484	1484	ps
	t_{PCOUT}	511	536	910	983	1056	1056	ps
1.5V	t_{PI}	790	828	1439	1497	1556	1556	ps
	t_{PCOUT}	576	604	977	1052	1128	1128	ps
LVCMOS	t_{PI}	581	609	1222	1228	1282	1282	ps
	t_{PCOUT}	367	385	760	783	854	854	ps
SSTL_2_CLASS_I	t_{PI}	533	558	990	1015	1040	1040	ps
	t_{PCOUT}	319	334	528	570	612	612	ps
SSTL_2_CLASS_II	t_{PI}	533	558	990	1015	1040	1040	ps
	t_{PCOUT}	319	334	528	570	612	612	ps
SSTL_18_CLASS_I	t_{PI}	577	605	1027	1035	1045	1045	ps
	t_{PCOUT}	363	381	565	590	617	617	ps
SSTL_18_CLASS_II	t_{PI}	577	605	1027	1035	1045	1045	ps
	t_{PCOUT}	363	381	565	590	617	617	ps

Table 5–43. Cyclone II I/O Output Delay for Row Pins (Part 1 of 4)

I/O Standard	Drive Strength	Parameter	Fast Corner		–6 Speed Grade	–7 Speed Grade (2)	–7 Speed Grade (3)	–8 Speed Grade	Unit
			Industrial /Auto-motive	Commer-cial					
LVTTL	4 mA	t_{OP}	1343	1408	2539	2694	2885	2891	ps
		t_{DIP}	1467	1540	2747	2931	3158	3158	ps
	8 mA	t_{OP}	1198	1256	2411	2587	2756	2762	ps
		t_{DIP}	1322	1388	2619	2824	3029	3029	ps
	12 mA	t_{OP}	1156	1212	2282	2452	2614	2620	ps
		t_{DIP}	1280	1344	2490	2689	2887	2887	ps
	16 mA	t_{OP}	1124	1178	2286	2455	2618	2624	ps
		t_{DIP}	1248	1310	2494	2692	2891	2891	ps
	20 mA	t_{OP}	1112	1165	2245	2413	2574	2580	ps
		t_{DIP}	1236	1297	2453	2650	2847	2847	ps
	24 mA (1)	t_{OP}	1105	1158	2253	2422	2583	2589	ps
		t_{DIP}	1229	1290	2461	2659	2856	2856	ps
LVCMOS	4 mA	t_{OP}	1200	1258	2231	2396	2555	2561	ps
		t_{DIP}	1324	1390	2439	2633	2828	2828	ps
	8 mA	t_{OP}	1125	1179	2260	2429	2591	2597	ps
		t_{DIP}	1249	1311	2468	2666	2864	2864	ps
	12 mA (1)	t_{OP}	1106	1159	2217	2383	2543	2549	ps
		t_{DIP}	1230	1291	2425	2620	2816	2816	ps
2.5V	4 mA	t_{OP}	1126	1180	2350	2477	2598	2604	ps
		t_{DIP}	1250	1312	2558	2714	2871	2871	ps
	8 mA (1)	t_{OP}	1105	1158	2177	2296	2409	2415	ps
		t_{DIP}	1229	1290	2385	2533	2682	2682	ps

Table 5–44. Maximum Input Clock Toggle Rate on Cyclone II Devices (Part 2 of 2)

I/O Standard	Maximum Input Clock Toggle Rate on Cyclone II Devices (MHz)								
	Column I/O Pins			Row I/O Pins			Dedicated Clock Inputs		
	–6 Speed Grade	–7 Speed Grade	–8 Speed Grade	–6 Speed Grade	–7 Speed Grade	–8 Speed Grade	–6 Speed Grade	–7 Speed Grade	–8 Speed Grade
DIFFERENTIAL_SSTL_18_CLASS_I	500	500	500	500	500	500	500	500	500
DIFFERENTIAL_SSTL_18_CLASS_II	500	500	500	500	500	500	500	500	500
1.8V_DIFFERENTIAL_HSTL_CLASS_I	500	500	500	500	500	500	500	500	500
1.8V_DIFFERENTIAL_HSTL_CLASS_II	500	500	500	500	500	500	500	500	500
1.5V_DIFFERENTIAL_HSTL_CLASS_I	500	500	500	500	500	500	500	500	500
1.5V_DIFFERENTIAL_HSTL_CLASS_II	500	500	500	500	500	500	500	500	500
LVPECL	—	—	—	—	—	—	402	402	402
LVDS	402	402	402	402	402	402	402	402	402
1.2V_HSTL	110	90	80	—	—	—	110	90	80
1.2V_DIFFERENTIAL_HSTL	110	90	80	—	—	—	110	90	80

Table 5–45. Maximum Output Clock Toggle Rate on Cyclone II Devices (Part 1 of 4)

I/O Standard	Drive Strength	Maximum Output Clock Toggle Rate on Cyclone II Devices (MHz)								
		Column I/O Pins *(1)*			Row I/O Pins *(1)*			Dedicated Clock Outputs		
		–6 Speed Grade	–7 Speed Grade	–8 Speed Grade	–6 Speed Grade	–7 Speed Grade	–8 Speed Grade	–6 Speed Grade	–7 Speed Grade	–8 Speed Grade
LVTTL	4 mA	120	100	80	120	100	80	120	100	80
	8 mA	200	170	140	200	170	140	200	170	140
	12 mA	280	230	190	280	230	190	280	230	190
	16 mA	290	240	200	290	240	200	290	240	200
	20 mA	330	280	230	330	280	230	330	280	230
	24 mA	360	300	250	360	300	250	360	300	250

PLL Specifications

See the *DC & Switching Characteristics* chapter in Volume 1 of the *Cyclone II Device Handbook* for information on PLL timing specifications.

Clocking

Cyclone II devices provide up to 16 dedicated clock pins (`CLK[15..0]`) that can drive the global clock networks. The smaller Cyclone II devices (EP2C5 and EP2C8 devices) support four dedicated clock pins on each side (left and right) capable of driving a total of eight global clock networks, while the larger devices (EP2C15 devices and larger) support four clock pins on all four sides of the device. These clock pins can drive a total of 16 global clock networks.

Table 7–7 shows the number of global clocks available across the Cyclone II family members.

Table 7–7. Number of Global Clocks Available in Cyclone II Devices

Device	Number of Global Clocks
EP2C5	8
EP2C8	8
EP2C15	16
EP2C20	16
EP2C35	16
EP2C50	16
EP2C70	16

Global Clock Network

Global clocks drive throughout the entire device, feeding all device quadrants. All resources within the device (IOEs, logic array blocks (LABs), dedicated multiplier blocks, and M4K memory blocks) can use the global clock networks as clock sources. These clock network resources can also be used for control signals, such as clock enables and synchronous or asynchronous clears fed by an external pin. Internal logic can also drive the global clock networks for internally generated global clocks and asynchronous clears, clock enables, or other control signals with high fan-out.

case writing is controlled only by the write enable signals. There is no clear port to the byte enable registers. M4K blocks support byte enables when the write port has a data width of 1, 2, 4, 8, 9, 16, 18, 32, or 36 bits. When using data widths of 1, 2, 4, 8, and 9 bits, the byte enable behaves as a redundant write enable because the data width is less than or equal to a single byte. Table 8–3 summarizes the byte selection.

Table 8–3. Byte Enable for Cyclone II M4K Blocks *Note (1)*

byteena[3..0]	Affected Bytes								
	datain ×1	datain ×2	datain ×4	datain ×8	datain ×9	datain ×16	datain ×18	datain ×32	datain ×36
[0] = 1	[0]	[1..0]	[3..0]	[7..0]	[8..0]	[7..0]	[8..0]	[7..0]	[8..0]
[1] = 1	-	-	-	-	-	[15..8]	[17..9]	[15..8]	[17..9]
[2] = 1	-	-	-	-	-	-	-	[23..16]	[26..18]
[3] = 1	-	-	-	-	-	-	-	[31..24]	[35..27]

Note to Table 8–3:
(1) Any combination of byte enables is possible.

Table 8–4 shows the byte enable port control for true dual-port mode.

Table 8–4. Byte Enable Port Control for True Dual-Port Mode

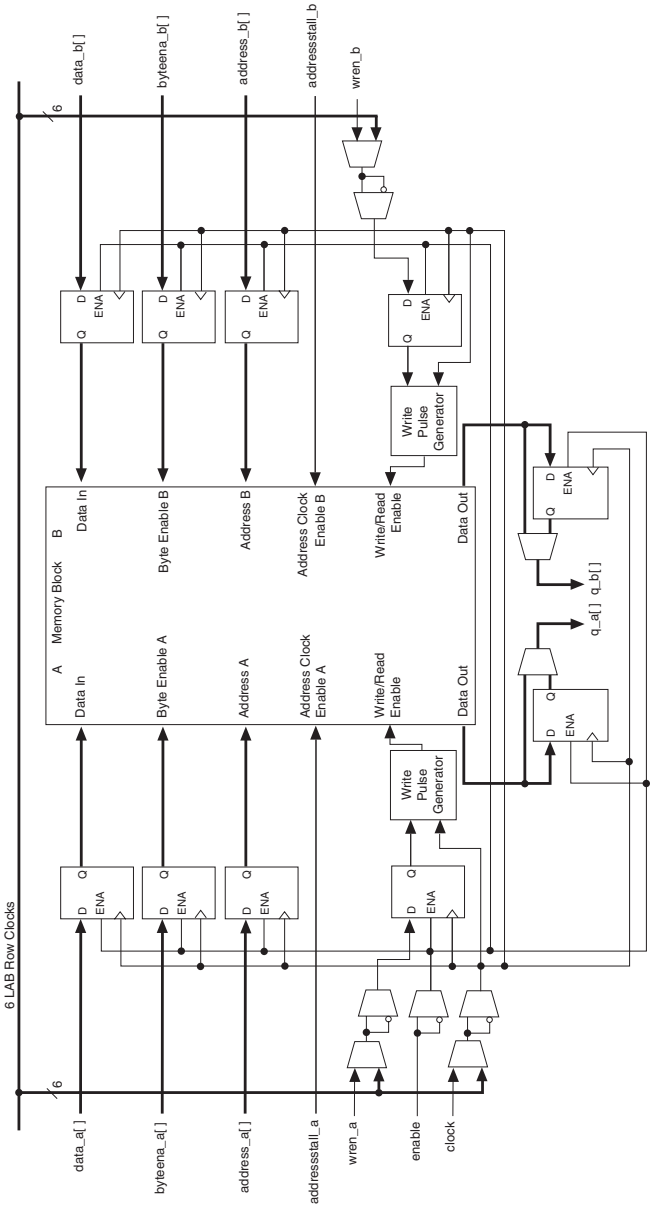
byteena [3:0]	Affected Port
[1:0]	Port A *(1)*
[3:2]	Port B *(1)*

Note to Table 8–4:
(1) For any data width up to ×18 for each port.

Figure 8–2 shows how the `wren` and `byteena` signals control the operations of the RAM.

When a byte enable bit is de-asserted during a write cycle, the corresponding data byte output appears as a "don't care" or unknown value. When a byte enable bit is asserted during a write cycle, the corresponding data byte output is the newly written data.

Figure 8–18. Cyclone II Single-Clock Mode in True Dual-Port Mode *Note (1)*



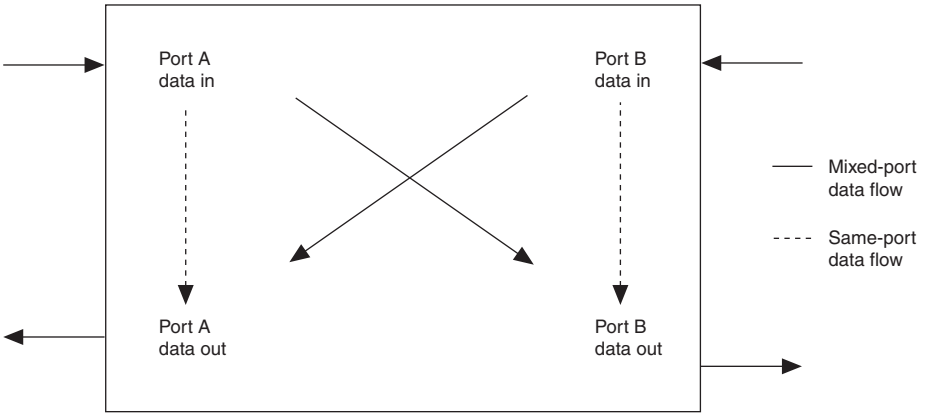
Note to Figure 8–18:

(1) Violating the setup or hold time on the memory block address registers could corrupt memory contents. This applies to both read and write operations.

Read-During-Write Operation at the Same Address

The "Same-Port Read-During-Write Mode" and "Mixed-Port Read-During-Write Mode" sections describe the functionality of the various RAM configurations when reading from an address during a write operation at that same address. There are two read-during-write data flows: same-port and mixed-port. Figure 8–21 shows the difference between these flows.

Figure 8–21. Cyclone II Read-During-Write Data Flow



Same-Port Read-During-Write Mode

For read-during-write operation of a single-port RAM or the same port of a true dual-port RAM, the new data is available on the rising edge of the same clock cycle on which it was written. Figure 8–22 shows a sample functional waveform. When using byte enables in true dual-port RAM mode, the outputs for the masked bytes on the same port are unknown (see Figure 8–2 on page 8–6). The non-masked bytes are read out as shown in Figure 8–22.

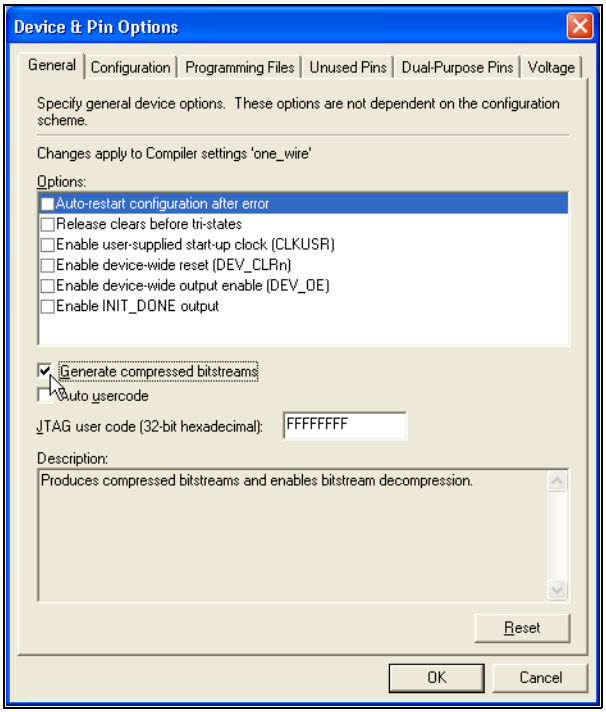
DQS pin to the DQ LE register does not necessarily match the delay from the DQ pin to the DQ LE register. Therefore, you must adjust the clock delay control circuitry to compensate for this difference in delays.

DQS Postamble

For external memory interfaces that use a bidirectional read strobe, such as DDR and DDR2 SDRAM, the DQS signal is low before going to or coming from the high-impedance state (see Figure 9–1). The state where DQS is low just after high-impedance is called the preamble and the state where DQS is low just before it goes to high-impedance is called the postamble. There are preamble and postamble specifications for both read and write operations in DDR and DDR2 SDRAM. If the Cyclone II device or the DDR/DDR2 SDRAM device does not drive the DQ and DQS pins, the signals go to a high-impedance state. Because a pull-up resistor terminates both DQ and DQS to V_{TT} (1.25 V for SSTL-2 and 0.9 V for SSTL-18), the effective voltage on the high-impedance line is either 1.25 V or 0.9 V. According to the JEDEC JESD8-9 specification for SSTL-2 I/O standard and the JESD8-15A specification for SSTL-18 I/O standard, this is an indeterminate logic level, and the input buffer can interpret this as either a logic high or logic low. If there is any noise on the DQS line, the input buffer may interpret that noise as actual strobe edges.

Cyclone II devices have non-dedicated logic that can be configured to prevent a false edge trigger at the end of the DQS postamble. Each Cyclone II DQS signal is connected to postamble logic that consists of a D flip flop (see Figure 9–9). This register is clocked by the shifted DQS signal. Its input is connected to ground. The controller needs to include extra logic to tell the reset signal to release the preset signal on the falling DQS edge at the start of the postamble. This disables any glitches that happen right after the postamble. This postamble logic is automatically implemented by the Altera MegaCore DDR/DDR2 SDRAM Controller in the LE register as part of the open-source datapath.

Figure 13–1. Enabling Compression for Cyclone II Bitstreams in Compiler Settings



You can also use the following steps to enable compression when creating programming files from the Convert Programming Files window.

1. Click **Convert Programming Files** (File menu).
2. Select the Programming File type. Only Programmer Object Files (**.pof**), SRAM HEXOUT, RBF, or TTF files support compression.
3. For POFs, select a configuration device.
4. Select **Add File** and add a Cyclone II SRAM Object File(s) (**.sof**).
5. Select the name of the file you added to the SOF Data area and click on **Properties**.
6. Check the **Compression** check box.

Reset Stage

When nCONFIG or nSTATUS are low, the device is in reset. After POR, the Cyclone II device releases nSTATUS. An external 10-kΩ pull-up resistor pulls the nSTATUS signal high, and the Cyclone II device enters configuration mode.

V_{CCINT} and V_{CCIO} of the banks where the configuration and JTAG pins reside need to be fully powered to the appropriate voltage levels in order to begin the configuration process.

Configuration Stage

The serial clock (DCLK) generated by the Cyclone II device controls the entire configuration cycle and provides the timing for the serial interface. Cyclone II devices use an internal oscillator to generate DCLK. Using the MSEL[] pins, you can select either a 20- or 40-MHz oscillator. Although you can select either 20- or 40-MHz oscillator when designing with serial configuration devices, the 40-MHz oscillator provides faster configuration times. There is some variation in the internal oscillator frequency because of the process, temperature, and voltage conditions in Cyclone II devices. The internal oscillator is designed such that its maximum frequency is guaranteed to meet EPCS device specifications.

Table 13–5 shows the AS DCLK output frequencies.

Table 13–5. AS DCLK Output Frequency *Note (1)*

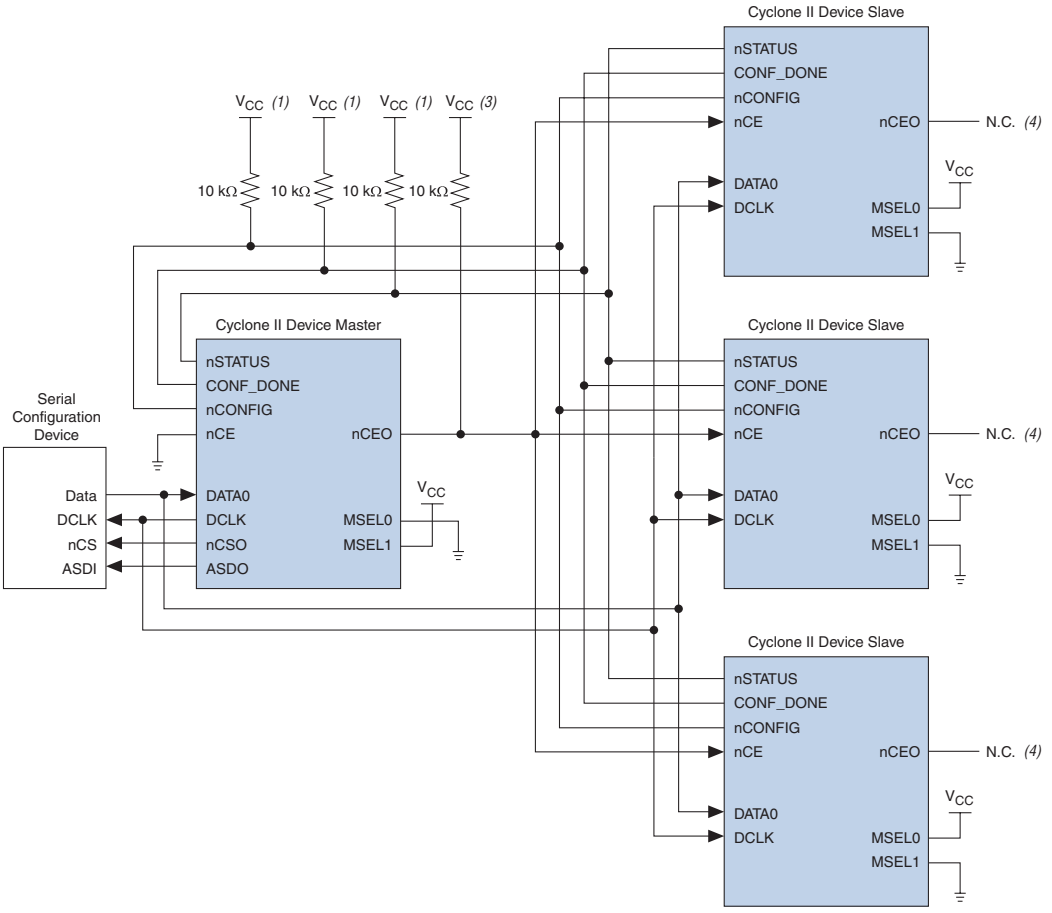
Oscillator Selected	Minimum	Typical	Maximum	Units
40 MHz	20	26	40	MHz
20 MHz	10	13	20	MHz

Note to Table 13–5:
(1) These values are preliminary.

In both AS and Fast AS configuration schemes, the serial configuration device latches input and control signals on the rising edge of DCLK and drives out configuration data on the falling edge. Cyclone II devices drive out control signals on the falling edge of DCLK and latch configuration data on the falling edge of DCLK.

In configuration mode, the Cyclone II device enables the serial configuration device by driving its nCSO output pin low, which connects to the chip select (nCS) pin of the configuration device. The Cyclone II device uses the serial clock (DCLK) and serial data output (ASDO) pins to send operation commands and/or read address signals to the serial

Figure 13–5. Multiple Device AS Configuration When FPGAs Receive the Same Data with Multiple SOFs



Notes to Figure 13–5:

(1) Connect the pull-up resistors to a 3.3-V supply.

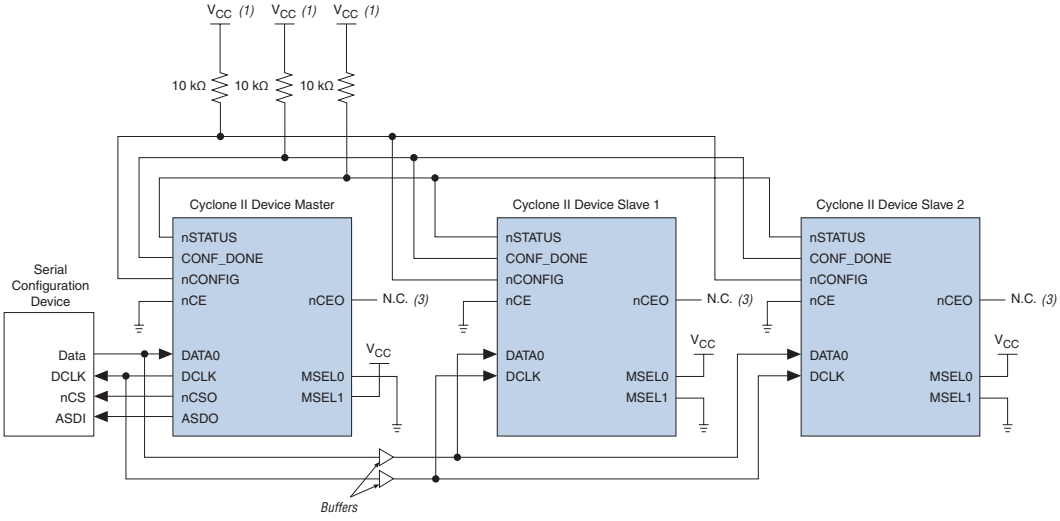
(2) Connect the pull-up resistor to the V_{CCIO} supply voltage of I/O bank that the nCEO pin resides in.

(3) The nCEO pin can be left unconnected or used as a user I/O pin when it does not feed another device's nCE pin.

Single SOF

The second method configures both the master and slave Cyclone II devices with the same SOF. The serial configuration device stores one copy of the SOF file. This setup is shown in Figure 13–6 where the master is setup in AS mode, and the slave devices are setup in PS mode (MSEL=01). You could setup one or more slave devices in the chain and all the slave devices are setup in the same way as shown in Figure 13–6.

Figure 13–6. Multiple Device AS Configuration When FPGAs Receive the Same Data with a Single SOF



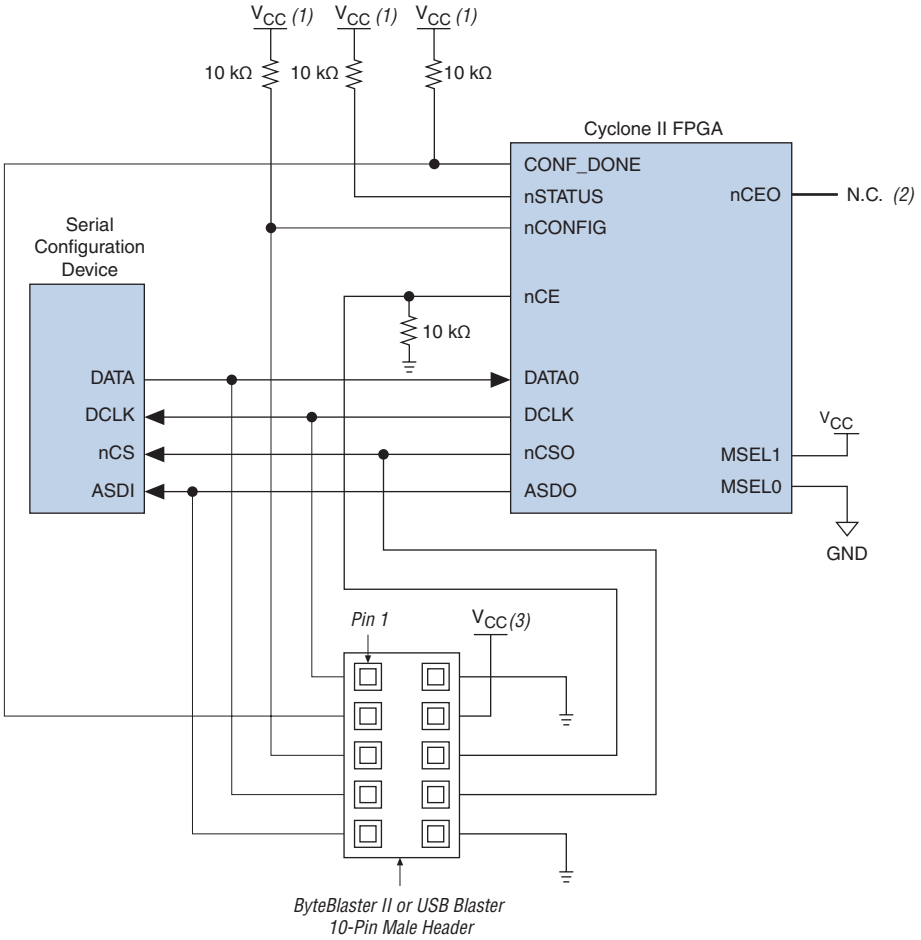
Notes to Figure 13–6:

(1) Connect the pull-up resistors to a 3.3-V supply.

(2) The nCEO pin can be left unconnected or used as a user I/O pin when it does not feed another device's nCE pin.

In this setup, all the Cyclone II devices in the chain are connected for concurrent configuration. This can reduce the AS configuration time because all the Cyclone II devices are configured in one configuration cycle. Connect the nCE input pins of all the Cyclone II devices to ground. You can either leave the nCEO output pins on all the Cyclone II devices unconnected or use the nCEO output pins as normal user I/O pins. The DATA and DCLK pins are connected in parallel to all the Cyclone II devices.

Figure 13–7. In-System Programming of Serial Configuration Devices



Notes to Figure 13–7:

(1) Connect these pull-up resistors to 3.3-V supply.

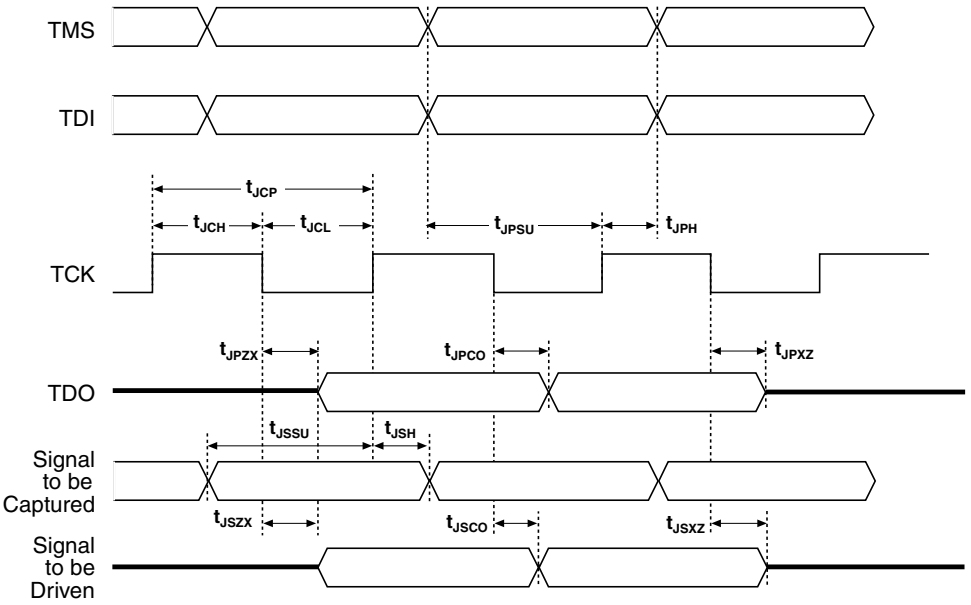
(2) The nCEO pin can be left unconnected or used as a user I/O pin when it does not feed other device's nCE pin.

(3) Power up the ByteBlaster II or USB Blaster cable's V_{CC} with a 3.3-V supply.

You can use the Quartus II software with the APU and the appropriate configuration device programming adapter to program serial configuration devices. All serial configuration devices are offered in an 8-pin or 16-pin small outline integrated circuit (SOIC) package and can be programmed using the PLMSEPC-8 adapter.

When the TAP controller is in the TEST_LOGIC/RESET state, the BST circuitry is disabled, the device is in normal operation, and the instruction register is initialized with IDCODE as the initial instruction. At device power-up, the TAP controller starts in this TEST_LOGIC/RESET state. In addition, forcing the TAP controller to the TEST_LOGIC/RESET state is done by holding TMS high for five TCK clock cycles. Once in the TEST_LOGIC/RESET state, the TAP controller remains in this state as long as TMS is held high (while TCK is clocked). Figure 14–6 shows the timing requirements for the IEEE Std. 1149.1 signals.

Figure 14–6. IEEE Std. 1149.1 Timing Waveforms



To start IEEE Std. 1149.1 operation, select an instruction mode by advancing the TAP controller to the shift instruction register (SHIFT_IR) state and shift in the appropriate instruction code on the TDI pin. The waveform diagram in Figure 14–7 represents the entry of the instruction code into the instruction register. It shows the values of TCK, TMS, TDI, TDO, and the states of the TAP controller. From the RESET state, TMS is clocked with the pattern 01100 to advance the TAP controller to SHIFT_IR.